TXM-315-LR TXM-433-LR TXM-418-LR



GUIDE

## DATA

# LR SERIES TRANSMITTER MODULE

出版 LR SERIES TI 息 DESCRIPTION
The LR Series trans transcommand information 样 transferring data at rates of up to 10,000bps at fidistances of up to 3,000 feet. Applications operating Cover shorter distances or at lower data rates will also benefit from increased link reliability and superior noise immunity. The transmitter's synthesized 搜加 pulling. Housed in a tiny reflow-compatible frequency accuracy and minimizes the affects of reliable wireless link is formed, effective wireless transfer of serial data, control, or components (except an antenna), which greatly architecture delivers outstanding stability and command information in the favorable 260-470MHz simplifies integration and lowers assembly costs. SMD package, the transmitter requires no external band. When paired with a compatible Linx receiver, a The LR Series transmitter is ideal for the costcapable <u>o</u>

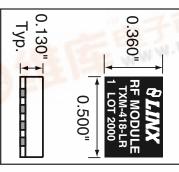


Figure 1: Package Dimensions

#### **FEATURES**

- Long range
- Low cost
- PLL-synthesized architecture
- Data rates to 10,000bps Direct serial interface
- No external RF components needed

No production tuning

Power-down function

Compact surface mount package Wide temperature range

Low voltage (2.1 to 3.6VDC) Low power consumption

## APPLICATIONS INCLUDE

Keyless Entry Remote Control

查询RXM-315-LR供应商

- Garage / Gate Openers
- **Lighting Control**
- Medical Monitoring / Call Systems
- Periodic Data Transfer Remote Industrial Monitoring
- Home / Industrial Automation
- Fire / Security Alarms
- Remote Status / Position Sensing
- Long-Range RFID
- Wire Elimination

## 

	CADENING INFORMATION
PART #	DESCRIPTION
TXM-315-LR	Transmitter 315MHz
TXM-418-LR	Transmitter 418MHz
TXM-433-LR	Transmitter 433MHz
RXM-315-LR	Receiver 315MHz
RXM-418-LR	Receiver 418MHz
RXM-433-LR	Receiver 433MHz
EVAL-***-LR	Basic Evaluation Kit
*** = Frequency	
Transmitters are su	Transmitters are supplied in tubes of 50 pcs.

找 <mark>,PDF</mark>
维库————————————————————————————————————

## **ELECTRICAL SPECIFICATIONS**

POWER SUPPLY         V <sub>CC</sub> 2.11         3.0         3.6         VDC         2.1           Operating Voltage         V <sub>CC</sub> 2.1         3.0         3.6         VDC            Supply Current:         I <sub>CC</sub> -         3.4         -         mA         1,2           Logic High         -         -         1.8         -         mA         1,2           Towar-Down Current         I <sub>PDN</sub> -         1.8         -         mA         1,2           Transmit Frequency Range:         F <sub>C</sub> -         4.18         -         mA         -           TXM-315-LR         -         -         4.18         -         MHz         -           TXM-433-LR         -         -         433.92         -         MHz         -           Center Frequency Accuracy         -         -         -         433.92         -         MHz         -           City Duly Dower         -         -         -         433.92         -         MHz         -           Coulput Power         -         -         -         -         -         -         -         -         -         -         -	Parameter	Designation	Min.	Typical	Max.	Units	Notes
Ig Voltage         V <sub>CC</sub> 2.1         3.0         3.6         VDC           Current:         I <sub>CC</sub> -         3.4         -         mA           High         -         5.1         -         mA           Low         I <sub>PDN</sub> -         5.1         -         mA           Jown Current         I <sub>PDN</sub> -         5.0         -         mA           MITTER SECTION         -         -         5.0         -         mMHz           418-LR         -         -         -         MHz         -           418-LR         -         -         -         MHz         -           419-LR         -         -         -         -         MMHz           433-LR         -         -         -         MHz         - <t< td=""><td>POWER SUPPLY</td><td></td><td></td><td></td><td></td><td></td><td></td></t<>	POWER SUPPLY						
Courrent:         I <sub>CC</sub> —         3.4         —         mA           High         —         5.1         —         mA           Low         —         5.1         —         mA           Down Current         I <sub>PDN</sub> —         5.0         —         mA           WINTER SECTION         —         315         —         mMHz           18-LR         —         418         —         mMHz           418-LR         —         418         —         MHz           418-LR         —         418         —         MHz           133-LR         —         433.92         —         MHz           149-LR         —         —         40         —         MHz           149-Weigh         —         —         40         —         HB           16 cernissions         P         P         —         —         —         40         D           <	Operating Voltage	$V_{\rm cc}$	2.1	3.0	3.6	VDC	ı
High Low         —         5.1         —         mA Low           Down Current         I <sub>PDN</sub> —         1.8         —         mA           MITTER SECTION         FC         —         31.8         —         mA           315-LR         —         418         —         MHz           418-LR         —         418         —         MHz           433-LR         —         433.92         —         MHz           7-requency Accuracy         —         -50         —         418         —         MHz           433-LR         —         —         433.92         —         MHz         MHz           7-requency Accuracy         —         -60         —         418         —         MHz           433-LR         —         —         433.92         —         MHz           135-LR         —         —         40         0.0         +4         MHz           2-cwer Control Range         —         —         BC         —         +10         dB           1c Emissions         PH         V <sub>L</sub> —         0.25         VDC           1cbw         V <sub>L</sub> —         0.	Supply Current:	lcc	I	3.4	ı	mA	1,2
Low         —         1.8         —         mA           Num Current         I <sub>PDN</sub> —         1.8         —         mA           MITTER SECTION         F <sub>C</sub> 5.0         —         mA           315-LR         —         4.18         —         mA           418-LR         —         4.18         —         MHz           418-LR         —         4.18         —         MHz           433-LR         —         4.18         —         MHz           433-LR         —         4.0         4.18         —         MHz           7-equency Accuracy         —         -50         —         418         —         MHz           433-LR         —         —         40         0.0         +4         MHz           2-wer Control Range         —         —         -80         —         +10         dB           1c Emissions         P <sub>H</sub> -36         —         —         -         dBo           1cbw         V <sub>L</sub> —         —         0.25         VDC           1cbw         V <sub>L</sub> —         —         0.25         VDC           1cbw <td>Logic High</td> <td></td> <td>ı</td> <td>5.1</td> <td>ı</td> <td>mA</td> <td>N</td>	Logic High		ı	5.1	ı	mA	N
Down Current         I <sub>PDN</sub> -         5.0         -         nA           MITTER SECTION         F <sub>C</sub> -         315         -         MHz           315-LR         -         418         -         MHz           418-LR         -         418         -         MHz           433-LR         -         433.92         -         MHz           7-equency Accuracy         -         -50         -         433.92         -         MHz           7-equency Accuracy         -         -         -50         -         433.92         -         MHz           7-equency Accuracy         -         -         -         433.92         -         MHz           133-LR         -         -         -         400.0         +4         dBm           10-wer Control Range         -         -         -         0.2         +10         dB           10-wer Control Range         P <sub>H</sub> -36         -         +10         dB           10-wer Control Range         P <sub>UL</sub> -         -         0.25         VDC           10-wer Control Range         V <sub>IL</sub> -         -         0.25         VDC	Logic Low		I	1.8	ı	mA	ı
WITTER SECTION         FC	Power-Down Current	I <sub>PDN</sub>	ı	5.0	ı	nΑ	ı
t Frequency Range:         F <sub>C</sub> —         315-LR         —         MHz           418-LR         —         418         —         MHz           433-LR         —         418         —         MHz           5-equency Accuracy         —         -50         —         433.92         —         MHz           5-equency Accuracy         —         -50         —         433.92         —         MHz           5-equency Accuracy         —         -50         —         433.92         —         MHz           5-equency Accuracy         —         -50         —         450         kHz         MHz           5-equency Accuracy         —         -50         —         +50         kHz         MHz           5-equency Accuracy         —         -80         —         +10         dBm         MHz           5-equency Accuracy         —         —         -80         —         +10         dBm         dBm         -         MHz         dBm         -         -         dBm         -         -         dBm         -         -         -         -         DC         -         DC         -         -         -         - </td <td>TRANSMITTER SECTION</td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td>	TRANSMITTER SECTION						
315-LR       —       315       —       MHz         418-LR       —       418       —       MHz         433-LR       —       418       —       MHz         1433-LR       —       418       —       MHz         1438-Power       —       -50       —       433.92       —       MHz         2-wer Control Range       —       -80       —       +10       dB         ic Emissions       P <sub>H</sub> -36       —       +10       dB         Low       V <sub>L</sub> —       DC       —       40       bps         Low       V <sub>L</sub> —       —       0.25       VDC         High       V <sub>H</sub> V <sub>CC</sub> -0.25       —       VDC         NA PORT       V <sub>H</sub> V <sub>CC</sub> -0.25       —       VDC         V <sub>H</sub> V <sub>CC</sub> -0.25       —       —       VDC         Vac or PDN       —       —       50       —       Ω         Terr Turn-On Time:       —       —       50       —       MSec         S <sub>C</sub> or PDN       —       —       —       30.0       nS         NMEC       —       —       —       9	Transmit Frequency Range:	F <sub>C</sub>					
418-LR       —       418       —       MHz         433-LR       —       438.92       —       MHz         5ower       Po       -4       0.0       +4       dBm         5ower Control Range       —       -80       —       +10       dB         ic Emissions       PH       -36       —       +10       dB         but       VIL       —       DC       —       40,000       bps         Low       VIL       —       DC       —       40Bc         Low       VIL       —       —       0.25       VDC         High       VIL       —       —       0.25       VDC         NA PORT       VIL       —       —       0.25       VDC         VAPOO       VIL       —       50       —       VDC         VAPOOR       —       —       0.25       VDC         VBC       O.25       —       —       VDC         VBC       —       —       —       Q         VBC       —       —       —       Q         VBC       —       —       —       Q         VBC       — <td>TXM-315-LR</td> <td></td> <td>I</td> <td>315</td> <td>ı</td> <td>MHz</td> <td>ı</td>	TXM-315-LR		I	315	ı	MHz	ı
433-LR       —       433.92       —       MHz         Trequency Accuracy       —       -50       —       +50       kHz         Power       Po       -4       0.0       +4       dBm         Power Control Range       —       -80       —       +10       dB         ic Emissions       P <sub>H</sub> -36       —       +10       dB         but       V <sub>IL</sub> —       DC       —       10,000       bps         Low       V <sub>IL</sub> —       —       0.25       VDC         Down Input:       V <sub>IL</sub> —       —       0.25       VDC         Low       V <sub>IL</sub> —       —       0.25       VDC         NA PORT       V <sub>IL</sub> —       —       0.25       VDC         VA PORT       —       50       —       Ω         tter Turn-On Time:       —       —       50       —       Ω         por or PDN       —       —       —       0.2       mSec         por or PDN       —       —       —       0.0       mSec         por or PDN       —       —       —       1.0       —       mSec	TXM-418-LR		I	418	ı	MHz	ı
Trequency Accuracy         -         -50         -         +50         kHz           Power         Po         -4         0.0         +4         dBm           Power Control Range         -         -80         -         +10         dB           Ic Emissions         P <sub>H</sub> -36         -         -         dBc           Dut         -         DC         -         10,000         bps           Low         V <sub>IL</sub> -         -         0.25         VDC           Down Input:         V <sub>IL</sub> -         -         0.25         VDC           Low         V <sub>IL</sub> -         -         0.25         VDC           NA PORT         V <sub>IL</sub> -         -         0.25         VDC           VA PORT         -         50         -         Q           Iter Turn-On Time:         -         -         50         -         Q           Total inn Delay         -         -         1.0         -         mSec           NMENTAL         -         -         -         30.0         nS           Port Delay         -         -         -         +85         °C	TXM-433-LR		I	433.92	ı	MHz	ı
Power Control Range         Po         -4         0.0         +4         dBm           Power Control Range         -         -80         -         +10         dB           Ic Emissions         P <sub>H</sub> -36         -         +10         dB           Ite         -         DC         -         10,000         bps           Low         V <sub>IL</sub> -         -         0.25         VDC           Down Input:         V <sub>IL</sub> -         -         0.25         VDC           Low         V <sub>IL</sub> -         -         0.25         VDC           NA PORT         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           VA PORT         -         50         -         Q           Iter Turn-On Time:         -         50         -         Q           Toro or PDN         -         -         1.0         -         mSec           NMENTAL         -         -         1.0         -         mSec           NMENTAL         -         -         -         +85         °C	Center Frequency Accuracy	I	-50	I	+50	ΚΗz	ı
Power Control Range         -         -80         -         +10         dB           ic Emissions         P <sub>H</sub> -36         -         +10         dBc           but         -         DC         -         10,000         bps           but         V <sub>IL</sub> -         -         0.25         VDC           high         V <sub>IL</sub> -         -         0.25         VDC           bown Input:         V <sub>IL</sub> -         -         0.25         VDC           Low         V <sub>IL</sub> -         -         0.25         VDC           NA PORT         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           VA PORT         -         50         -         Q           tter Turn-On Time:         -         50         -         Q           ter Turn-On Time:         -         -         1.0         -         mSec           part in Delay         -         -         -         30.0         nS           part in Delay         -         -         -         40         -         +85         °C	Output Power	Ро	-4	0.0	+4	dBm	N
ic Emissions         P <sub>H</sub> and teter and tet	Output Power Control Range	ı	-80	I	+10	dВ	ω
tite         —         DC         —         10,000         bps           but:         V <sub>IL</sub> —         —         0.25         VDC           Low         V <sub>IH</sub> V <sub>CC</sub> -0.25         —         —         VDC           Down Input:         V <sub>IL</sub> —         —         0.25         VDC           Low         V <sub>IL</sub> —         —         0.25         VDC           High         V <sub>IH</sub> V <sub>CC</sub> -0.25         —         0.25         VDC           NA PORT         V <sub>IH</sub> V <sub>CC</sub> -0.25         —         —         VDC           VA PORT         V <sub>IH</sub> V <sub>CC</sub> -0.25         —         —         VDC           VA PORT         —         50         —         VDC           Value         —         50         —         Ω           Iter Turn-On Time:         —         —         —         MSec           DNMENTAL         —         —         —         mSec           NMEROTAL         —         —         —         +85         °C	Harmonic Emissions	$P_{H}$	-36	ı	ı	dBc	ı
Dut:         V <sub>IL</sub> -         -         0.25         VDC           High         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           Down Input:         V <sub>IL</sub> -         -         0.25         VDC           Low         V <sub>IL</sub> -         -         0.25         VDC           High         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           NA PORT         -         50         -         VDC           Iter Tum-On Time:         -         50         -         Ω           Iter Tum-On Time:         -         -         1.0         -         mSec           Sc or PDN         -         -         1.0         -         mSec           NMMENTAL         -         -         -         485         °C	Data Rate	I	DC	I	10,000	bps	ı
Low         V <sub>IL</sub> -         -         0.25         VDC           High         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           Down Input:         V <sub>IL</sub> -         -         0.25         VDC           Low         V <sub>IL</sub> -         -         0.25         VDC           High         V <sub>IL</sub> -         -         -         VDC           NA PORT         -         50         -         VDC           NA PORT         -         50         -         Ω           Iter Tum-On Time:         -         50         -         Ω           Iter Tum-On Time:         -         -         1.0         -         mSec           NAMENTAL         -         -         -         30.0         nS           NAMENTAL         -         -         -         +85         °C	Data Input:						
High         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           Down Input:         V <sub>IL</sub> -         -         0.25         VDC           Low         V <sub>IL</sub> -         -         0.25         VDC           High         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           NA PORT         -         50         -         -         VDC           NA PORT         -         50         -         -         Ω           Iter Turn-On Time:         -         -         1.0         -         mSec           Sc or PDN         -         -         -         1.0         -         mSec           NMMENTAL         -         -         -         30.0         nS         -           YER         -         -         -         -         +85         °C	Logic Low	<b>&lt;</b>	I	ı	0.25	VDC	ı
Down Input:         V <sub>IL</sub> -         -         0.25         VDC           Low         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           High         V <sub>IH</sub> V <sub>CC</sub> -0.25         -         -         VDC           NA PORT         -         50         -         Ω           Iter Turn-On Time:         -         50         -         Ω           Sc or PDN         -         -         1.0         -         mSec           Iation Delay         -         -         -         30.0         nS           NMENTAL         -         -         -         +85         °C	Logic High	< Ī	$V_{\rm cc}$ -0.25	ı	ı	VDC	ı
Low       V <sub>IL</sub> -       -       0.25       VDC         High       V <sub>IH</sub> V <sub>CC</sub> -0.25       -       -       VDC         NA PORT       ROUT       -       50       -       Ω         tter Turn-On Time:       -       -       1.0       -       mSec         po or PDN       -       -       1.0       -       mSec         nation Delay       -       -       -       30.0       nS         NMENTAL       -       -       -       +85       °C         19 Temperature Range       -       -       -       +85       °C	Power Down Input:						
High         V <sub>H</sub> V <sub>CC</sub> -0.25         -         -         VDC           NA PORT         R <sub>OUT</sub> -         50         -         Ω           tter Turn-On Time:         -         -         1.0         -         mSec           action Delay         -         -         -         30.0         nS           NNMENTAL         -         -         -         +85         °C	Logic Low	<b>∨</b> <sub>⊢</sub>	I	ı	0.25	VDC	ı
NA PORT         Agency         Agenc	Logic High	<b>&lt;</b> ∃	$V_{\rm cc}$ -0.25	I	ı	VDC	ı
put Impedance         R <sub>OUT</sub> -         50         -         Ω           tter Turn-On Time:         -         -         1.0         -         mSec           poc or PDN         -         -         1.0         -         mSec           nation Delay         -         -         -         30.0         nS           NNMENTAL         -         -         -         +85         °C	ANTENNA PORT						
tter Turn-On Time:       -       1.0       -       mSec         cor PDN       -       -       1.0       -       mSec         lation Delay       -       -       -       30.0       nS         NNMENTAL       -       -       -       +85       °C         19 Temperature Range       -       -       -40       -       +85       °C	RF Output Impedance	$R_{OUT}$	I	50	ı	Ω	4
1.0 - mSec 30.0 nS	TIMING						
1.0 - mSec 30.0 nS	Transmitter Turn-On Time:						
30.0 nS - +85 °C	Via V <sub>CC</sub> or PDN	ı	I	1.0	ı	mSec	4
40 - +85 °C	Modulation Delay	I	I	I	30.0	nS	4
40 - +85 °C	ENVIRONMENTAL						
	Operating Temperature Range	-	-40	-	+85	°C	4

Table 1: LR Series Transmitter Electrical Specifications

#### Notes

- With a 50% duty cycle.
   With a 750Ω resistor on LADJ.
   See graph on Page 3.
   Characterized, but not tested.

## **ABSOLUTE MAXIMUM RATINGS**

	+225°C for 10 seconds	25°C for 1	+22	Soldering Temperature
റ്	+90	ť	-40	Storage Temperature
റ്	+85	to	-40	Operating Temperature
VDC	$V_{CC} + 0.3$	to	-0.3	Any Input or Output Pin
VDC	+3.6	ťo	-0.3	Supply Voltage V <sub>CC</sub>

\*NOTE\* Exceeding any of the limits of this section may lead to permanent damage to the device. Furthermore, extended operation at these maximum ratings may reduce the life of this device.

## PERFORMANCE DATA

ground pins be connected to the These performance parameters are based on module operation at ground plane. operation. It is recommended all otherwise 25°C from a 3.0VDC supply unless necessary illustrates noted. Figure 2 ός the testing connections and

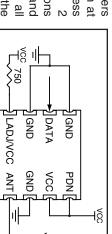


Figure 2: Test / Basic Application Circuit

# TYPICAL PERFORMANCE GRAPHS

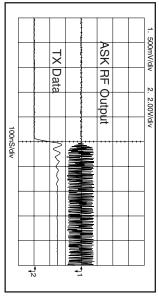


Figure 3: Modulation Delay

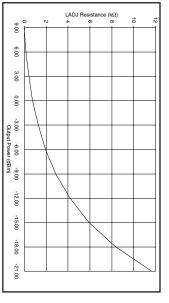


Figure 4: Output Power vs. LADJ Resistance

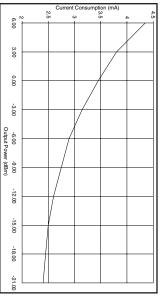


Figure 5: Current Consumption vs. Output Power (50% Duty Cycle)

### PIN ASSIGNMENTS

з <u>Ы</u> GND	2 DATA	1 NGND	
GND ☐ 6	VCC ☐ 7	PDN 3	
	YGND GND K	NOTA VCC C	YGND PDN Z

Figure 5: LR Series Transmitter Pinout (Top View)

### PIN DESCRIPTIONS

ω	7	6	5	4	3	2	1	Pin #
PDN	V <sub>CC</sub>	GND	ANT	LADJ/V <sub>CC</sub>	GND	DATA	GND	Name
Power Down. Pulling this line low will place the transmitter into a low-current state. The module will not be able to transmit a signal in this state.	Supply Voltage	Analog Ground	50-ohm RF Output	Level Adjust. This line can be used to adjust the output power level of the transmitter. Connecting to V <sub>CC</sub> will give the highest output, while placing a resistor to V <sub>CC</sub> will lower the output level (see Figure 4 on Page 3).	Analog Ground	Digital Data Input	Analog Ground	Description



#### \*CAUTION\*

This product incorporates numerous static-sensitive components. Always wear an ESD wrist strap and observe proper ESD handling procedures when working with this device. Failure to observe this precaution may result in module damage or failure.

## MODULE DESCRIPTION

The LR transmitter is a low-cost, high-performance synthesized ASK / Ox transmitter, capable of sending serial data at up to 10,000bps. Because to transmitter is completely self-contained, requiring an antenna as the orange and testing costs are reduced. When combined with an LR Series receiver reliable serial link is formed capable of transferring data over line-of-sedistances of up to 3,000 feet. The LR is housed in a compact surface-mou package that integrates easily into existing designs and is equally friendly prototyping and volume production. The module's low power consumption makes it ideal for battery-powered products. The transmitter is compatible with many other Linx receiver products, including the LC, LR, KH, and OEM productions where range is critical, the LR receiver is the bechoice due to its outstanding sensitivity. LR Series modules are capable meeting the regulatory requirements of domestic and international application

## THEORY OF OPERATION

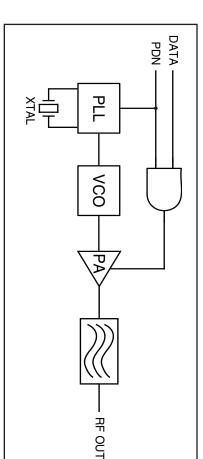


Figure 6: LR Series Transmitter Block Diagram

The LR Series transmitter is designed to generate 1mW of output power into 50-ohm single-ended antenna while suppressing harmonics and spuric emissions to within legal limits. The transmitter is comprised of a VCO locked a frequency synthesizer that is referenced to a high precision crystal. The outpof the VCO is amplified and buffered by an internal power amplifier. The amplifies switched by the incoming data to produce a modulated carrier. The carrier filtered to attenuate harmonics and then output to free space via the 50-ol antenna port.

The synthesized topology makes the module highly immune to the effects antenna port loading and mismatch. This reduces or eliminates frequer pulling, bit contraction, and other negative effects common to low-cutransmitter architectures. It also allows for reliable performance over a wipperating temperature range. Like its companion LR Series receiver, the Series transmitter delivers a significantly higher level of performance a reliability than the LC Series or other SAW-based devices, yet remains wismall and cost-effective.

Pag

#### THE DATA INPUT

The CMOS-compatible data input on Pin 2 is normally supplied with a serial bit stream from a microprocessor or encoder, but it can also be used with standard UARTs.

When a logic '1' is present on the DATA line and the PDN line is high, then the Power Amplifier (PA) will be activated and the carrier frequency will be sent to the antenna port. When a logic '0' is present on the DATA line or the PDN line is low, the PA is deactivated and the carrier is fully suppressed.

The DATA line should always be driven with a voltage that is common to the supply voltage present on Pin 7 ( $V_{\rm CC}$ ). The DATA line should never be allowed to exceed the supply voltage, as permanent damage to the module could occur.

### **USING THE PDN PIN**

The transmitter's Power Down (PDN) line can be used to power down the transmitter without the need for an external switch. It allows easy control of the transmitter's state from external components, such as a microcontroller. By periodically activating the transmitter, sending data, then powering down, the transmitter's average current consumption can be greatly reduced, saving power in battery operated applications.

The PDN line does not have an internal pull-up, so it will need to be pulled high or tied directly to  $V_{CC}$  to turn on the transmitter. The pull-up should be a minimum of  $30\mu A$  ( $10k\Omega$  or less). When the PDN line is pulled to ground, the transmitter will enter into a low-current (<5nA) power-down mode. When in this mode, the transmitter will be completely off and cannot perform any function.

**Note:** The voltage on the PDN line should not exceed V<sub>CC</sub>. When used with a higher voltage source, such as a 5V microcontroller, an open collector line should be used or a diode placed in series with the control line (anode toward the module). Either method avoids damage to the module by preventing 5V from being placed on the PDN line while allowing the line to be pulled low.

#### **USING LADJ**

The Level Adjust (LADJ) line allows the transmitter's output power to be easily adjusted for range control, lower power consumption, or to meet legal requirements. This is done by placing a resistor between  $V_{CC}$  and LADJ. The value of the resistor determines the output power level. When LADJ is connected to  $V_{CC}$ , the output power and current consumption will be at its maximum. Figure 4 on Page 3 shows a graph of the output power vs. LADJ resistance.

This line is very useful during FCC testing to compensate for antenna gain or other product-specific issues that may cause the output power to exceed legal limits. A variable resistor can be temporarily used so that the test lab can precisely adjust the output power to the maximum level allowed by law. The variable resistor's value can be noted and a fixed resistor substituted for final testing. Even in designs where attenuation is not anticipated, it is a good idea to place a resistor pad connected to LADJ and V<sub>CC</sub> so that it can be used if needed. For more sophisticated designs, LADJ can be also controlled by a DAC or digital potentiometer to allow precise and digitally variable output power control.

# POWER SUPPLY REQUIREMENTS

The module does not have an internal voltage regulator; therefore it requires clean, well-regulated power source. While it is preferable to power the unit from a battery, it can also be operated from a power supply as long as noise is le

than 20mV. Power supply noise can affect the transmitter modulation; therefore, providing a clean power supply for the module should be a high priority during design.

 $10\mu F$  tantalum capacitor from  $V_{CC}$  to ground will help in cases where the quality of the supply is poor. Note that the values may need to be adjusted depending on the noise present on the supply line.

A 10\O resistor in series with the supply followed by a

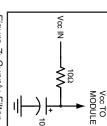


Figure 7: Supply Filter

### TRANSMITTING DATA

Once a reliable RF link has been established, the challenge becomes how effectively transfer data across it. While a properly designed RF link provid reliable data transfer under most conditions, there are still distinct difference from a wired link that must be addressed. Since the LR Series modules do reincorporate internal encoding or decoding, a user has tremendous flexibility how data is handled.

If you want to transfer simple control or status signals, such as button presses switch closures, and your product does not have a microprocessor on board, you wish to avoid protocol development, consider using an encoder and decod IC set. These chips are available from a range of manufacturers, including Lii They take care of all encoding and decoding functions and generally provide number of data pins to which switches can be directly connected. In additing address bits are usually provided for security and to allow the addressing multiple units independently. These ICs are an excellent way to bring ba remote control / status products to market quickly and inexpensive Additionally, it is a simple task to interface with inexpensive microprocesso such as the Microchip PIC, or one of many IR, remote control, or modem ICs

It is always important to separate what types of transmissions are technical possible from those that are legally allowable in the country of intendice operation. While the LR Series is ideally suited to the long range transfer control and command information, it can also be used with great success for the transfer of true variable data such as temperature, pressure, or sensor dathowever, the 260 - 470MHz band in which the module operates is regulated Part 15, Section 231 of the FCC regulations. Many types of transmission especially those involving automatic transmissions or variable data, may need be periodic. You may wish to review Application Notes AN-00125 and AN-001 along with Part 15, Section 231 of the FCC regulations for further details acceptable transmission content in the Unites States.

Another area of consideration is that of data structure or protocol. The dishould be formatted in a predictable way and should be able to deal with errodue to interference. This will ensure that the data is received and interpret correctly. If you are not familiar with the considerations for sending serial data a wireless environment, you will want to review Application Note AN-00160.

- age

## PROTOCOL GUIDELINES

While many RF solutions impose data formatting and balancing requirements, Linx RF modules do not encode or packetize the signal content in any manner. The received signal will be affected by such factors as noise, edge jitter, and interference, but it is not purposefully manipulated or altered by the modules. This gives the designer tremendous flexibility for protocol design and interface.

Despite this transparency and ease of use, it must be recognized that there are distinct differences between a wired and a wireless environment. Issues such as interference and contention must be understood and allowed for in the design process. To learn more about protocol considerations, we suggest you read Linx Application Note AN-00160.

Errors from interference or changing signal conditions can cause corruption of the data packet, so it is generally wise to structure the data being sent into small packets. This allows errors to be managed without affecting large amounts of data. A simple checksum or CRC could be used for basic error detection. Once an error is detected, the protocol designer may wish to simply discard the corrupt data or implement a more sophisticated scheme to correct it.

# INTERFERENCE CONSIDERATIONS

The RF spectrum is crowded and the potential for conflict with other unwanted sources of RF is very real. While all RF products are at risk from interference, its effects can be minimized by better understanding its characteristics.

Interference may come from internal or external sources. The first step is to eliminate interference from noise sources on the board. This means paying careful attention to layout, grounding, filtering, and bypassing in order to eliminate all radiated and conducted interference paths. For many products, this is straightforward; however, products containing components such as switching power supplies, motors, crystals, and other potential sources of noise must be approached with care. Comparing your own design with a Linx evaluation board can help to determine if and at what level design-specific interference is present.

External interference can manifest itself in a variety of ways. Low-level interference will produce noise and hashing on the output and reduce the link's overall range.

High-level interference is caused by nearby products sharing the same frequency or from near-band high-power devices. It can even come from your own products if more than one transmitter is active in the same area. It is important to remember that only one transmitter at a time can occupy a frequency, regardless of the coding of the transmitted signal. This type of interference is less common than those mentioned previously, but in severe cases it can prevent all useful function of the affected device.

Although technically it is not interference, multipath is also a factor to be understood. Multipath is a term used to refer to the signal cancellation effects that occur when RF waves arrive at the receiver in different phase relationships. This effect is a particularly significant factor in interior environments where objects provide many different signal reflection paths. Multipath cancellation results in lowered signal levels at the receiver and, thus, shorter useful distances for the link.

## TYPICAL APPLICATIONS

Figure 8 shows a circuit using a Linx MS Series encoder. This chip works we the Linx LICAL-DEC-MS001 decoder to provide simple remote cont capabilities. The decoder detects the transmission from the encoder, checks errors, and if everything is correct, replicates the encoder's inputs on its output. This makes registering key presses very simple.

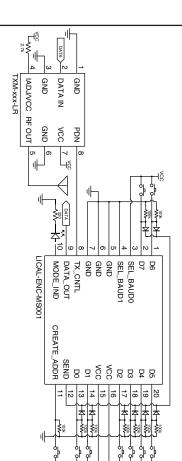


Figure 8: LR Transmitter and MS Encoder

Figure 9 shows a typical RS-232 circuit using the LR transmitter and a Max MAX232 chip. The MAX232 converts RS-232 compliant signals from a PC to serial data stream, which is then transmitted by the LR module.

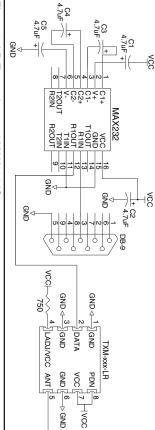


Figure 9: LR Transmitter and MAX232 IC

Figure 10 shows an example of using the LR transmitter with a Linx QS Ser USB module. The USB module converts low-speed USB compliant signals freat PC into a serial data stream, which is then transmitted by the LR module.

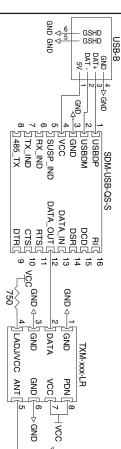


Figure 10: LR Transmitter and Linx QS Series USB Module

## **BOARD LAYOUT GUIDELINES**

If you are at all familiar with RF devices, you may be concerned about specialized board layout requirements. Fortunately, because of the care taken by Linx in designing the modules, integrating them is very straightforward. Despite this ease of application, it is still necessary to maintain respect for the RF stage and exercise appropriate care in layout and application in order to maximize performance and ensure reliable operation. The antenna can also be influenced by layout choices. Please review this data guide in its entirety prior to beginning your design. By adhering to good layout principles and observing some basic design rules, you will be on the path to RF success.

The adjacent figure shows the suggested PCB footprint for the module. The actual pad dimensions are shown in the Pad Layout section of this manual. A ground plane (as large as possible) should be placed on a lower layer of your PC board opposite the module. This ground plane can also be critical to the performance of your antenna, which will be discussed later. There should not be any ground or traces under the module on the same layer as the module, just bare PCB.

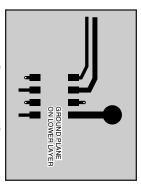


Figure 11: Suggested PCB Layout

During prototyping, the module should be soldered to a properly laid-out circuit board. The use of prototyping or "perf" boards will result in horrible performance and is strongly discouraged.

No conductive items should be placed within 0.15in of the module's top or sides.

Do not route PCB traces directly under the module. The underside of the module has numerous signal-bearing traces and vias that could short or couple to traces on the product's circuit board.

The module's ground lines should each have their own via to the ground plane and be as short as possible.

AM / OOK receivers are particularly subject to noise. The module should, as much as reasonably possible, be isolated from other components on your PCB, especially high-frequency circuitry such as crystal oscillators, switching power supplies, and high-speed bus lines. Make sure internal wiring is routed away from the module and antenna, and is secured to prevent displacement.

The power supply filter should be placed close to the module's V<sub>CC</sub> line.

In some instances, a designer may wish to encapsulate or "pot" the product. Many Linx customers have done this successfully; however, there are a wide variety of potting compounds with varying dielectric properties. Since such compounds can considerably impact RF performance, it is the responsibility of the designer to carefully evaluate and qualify the impact and suitability of such materials.

The trace from the module to the antenna should be kept as short as possible. A simple trace is suitable for runs up to 1/8-inch for antennas with wide bandwidth characteristics. For longer runs or to avoid detuning narrow bandwidth antennas, such as a helical, use a 50-ohm coax or 50-ohm microstrip transmission line as described in the following section.

## MICROSTRIP DETAILS

4 board material, the trace width would be 111 mils. The correct trace width c as a transmission line between the module and the antenna. The width is bas common form of transmission line is a coax cable, another is the microstrip. T be calculated for other widths and materials using the information below. Har and the dielectric constant of the board material. For standard 0.062in thick F on the desired characteristic impedance of the line, the thickness of the PC term refers to a PCB trace running over a ground plane that is designed to ser unless the antenna can be placed very close (<1/8in.) to the module. O changing its resonant bandwidth. In order to minimize loss and detuning, son place to another with minimal loss. This is a critical factor, especially in high www.linxtechnologies.com. software for calculating microstrip lines is also available on the Linx websi form of transmission line between the antenna and the module should be use module's antenna can effectively contribute to the length of the anteni frequency products like Linx RF modules, because the trace leading to A transmission line is a medium whereby RF energy is transferred from o

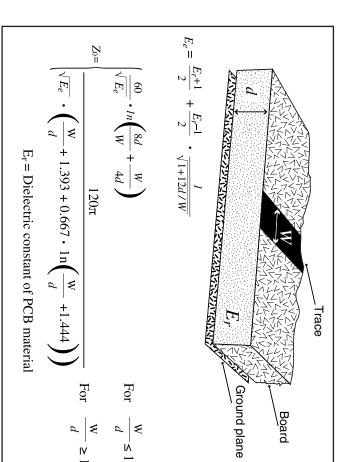


Figure 12: Microstrip Formulas

Dielectric Constant V	Width/Height (W/d)	Effective Dielectric Constant	1
4.80	1.8	3.59	
4.00	2.0	3.07	
2.55	3.0	2.12	

Page 10

#### PAD LAYOUT

The following pad layout diagram is designed to facilitate both hand and automated assembly.

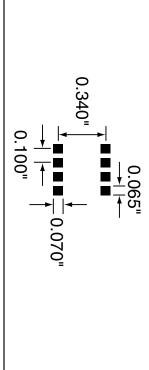


Figure 13: Recommended PCB Layout

## PRODUCTION GUIDELINES

The modules are housed in a hybrid SMD package that supports hand or automated assembly techniques. Since the modules contain discrete components internally, the assembly procedures are critical to ensuring the reliable function of the modules. The following procedures should be reviewed with and practiced by all assembly personnel.

#### HAND ASSEMBLY

Pads located on the bottom of the module are the primary mounting surface. Since these pads are inaccessible during mounting, castellations that run up the side of the module have been provided to facilitate solder wicking to the module's underside. This allows for very quick hand soldering for prototyping and small volume production.

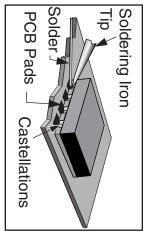


Figure 14: Soldering Technique

If the recommended pad guidelines have been followed, the pads will protrude slightly past the edge of the module. Use a fine soldering tip to heat the board pad and the castellation, then introduce solder to the pad at the module's edge. The solder will wick underneath the module, providing reliable attachment. Tack one module corner first and then work around the device, taking care not to exceed the times listed below.

# **Absolute Maximum Solder Times**

Hand-Solder Temp. TX +225°C for 10 Seconds
Hand-Solder Temp. RX +225°C for 10 Seconds
Recommended Solder Melting Point +180°C
Reflow Oven: +220°C Max. (See adjoining diagram)

## **AUTOMATED ASSEMBLY**

For high-volume assembly, most users will want to auto-place the modules. T modules have been designed to maintain compatibility with reflow processi techniques; however, due to the their hybrid nature, certain aspects of t assembly process are far more critical than for other component types.

Following are brief discussions of the three primary areas where caution must observed.

### **Reflow Temperature Profile**

The single most critical stage in the automated assembly process is the refl stage. The reflow profile below should not be exceeded, since excess temperatures or transport times during reflow will irreparably damage to modules. Assembly personnel will need to pay careful attention to the overprofile to ensure that it meets the requirements necessary to successfully reflect all components while still remaining within the limits mandated by the module. The figure below shows the recommended reflow oven profile for the module

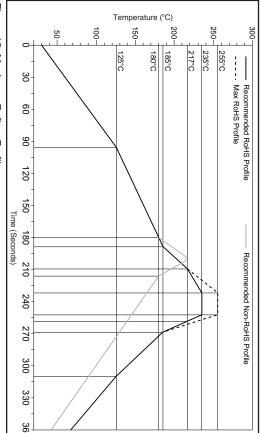


Figure 15: Maximum Reflow Profile

## Shock During Reflow Transport

Since some internal module components may reflow along with the componer placed on the board being assembled, it is imperative that the modules not subjected to shock or vibration during the time solder is liquid. Should a shobe applied, some internal components could be lifted from their pads, causi the module to not function properly.

#### Washability

The modules are wash resistant, but are not hermetically sealed. Li recommends wash-free manufacturing; however, the modules can be subject to a wash cycle provided that a drying time is allowed prior to applying electric power to the modules. The drying time should be sufficient to allow any moist that may have migrated into the module to evaporate, thus eliminating to potential for shorting damage during power-up or testing. If the wash contains contaminants, the performance may be adversely affected, even after drying.

## **ANTENNA CONSIDERATIONS**

The choice of antennas is a critical and often overlooked design consideration. The range, performance, and legality of an RF link are critically dependent upon the antenna. While adequate antenna performance can often be obtained by trial and error methods, antenna design and matching is a complex task. A professionally designed antenna, such as those from Linx, will

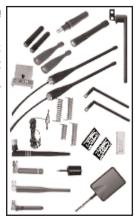


Figure 16: Linx Antennas

help ensure maximum performance and FCC compliance.

Linx transmitter modules typically have an output power that is slightly higher than the legal limits. This allows the designer to use an inefficient antenna, such as a loop trace or helical, to meet size, cost, or cosmetic requirements and still achieve full legal output power for maximum range. If an efficient antenna is used, then some attenuation of the output power will likely be needed. This can easily be accomplished by using the LADJ line or a T-pad attenuator. For more details on T-pad attenuator design, please see Application Note AN-00150.

A receiver antenna should be optimized for the frequency or band in which the receiver operates and to minimize the reception of off-frequency signals. The efficiency of the receiver's antenna is critical to maximizing range performance. Unlike the transmitter antenna, where legal operation may mandate attenuation or a reduction in antenna efficiency, the receiver's antenna should be optimized as much as is practical.

It is usually best to utilize a basic quarter-wave whip until your prototype product is operating satisfactorily. Other antennas can then be evaluated based on the cost, size, and cosmetic requirements of the product. You may wish to review Application Note AN-00500 "Antennas: Design, Application, Performance"

### ANTENNA SHARING

In cases where a transmitter and receiver module are combined to form a transceiver, it is often advantageous to share a single antenna. To accomplish this, an antenna switch must be used to provide isolation between the modules so that the full transmitter output power is not put on the sensitive front end of the receiver. There are a wide variety of antenna switches that are cost-effective and easy to use. Among

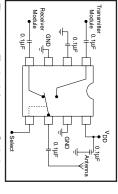


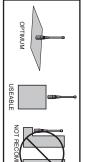
Figure 17: Typical Antenna Switch

the most popular are switches from Macom and NEC. Look for an antenna switch that has high isolation and low loss at the desired frequency of operation. Generally, the Tx or Rx status of a switch will be controlled by a product's microprocessor, but the user may also make the selection manually. In some cases, where the characteristics of the Tx and Rx antennas need to be different or antenna switch losses are unacceptable, it may be more appropriate to utilize two discrete antennas.

## **GENERAL ANTENNA RULES**

The following general rules should help in maximizing antenna performance

- Proximity to objects such as a user's hand, body, or metal objects will cause antenna to detune. For this reason, the antenna shaft and tip should positioned as far away from such objects as possible.
- 2. Optimum performance will be obtained from a 1/4- or 1/2-wave straight whip mounted at a right angle to the ground plane. In many cases, this isn't desirable for practical or ergonomic reasons, thus, an alternative antenna style such as a helical, loop, or patch may be utilized



helical, loop, or patch may be utilized *Figure 18: Ground Plane Orientation* and the corresponding sacrifice in performance accepted.

- 3. If an internal antenna is to be used, keep it away from other metal componen particularly large items like transformers, batteries, PCB tracks, and grou planes. In many cases, the space around the antenna is as important as t antenna itself. Objects in close proximity to the antenna can cause directuning, while those farther away will alter the antenna's symmetry.
- 4. In many antenna designs, particularly 1/4-wave whips, the ground plane acts as a counterpoise, forming, in essence, a 1/2-wave dipole. For this reason, adequate ground plane area is essential. The ground plane can be a metal case or ground-fill areas on a circuit board. Ideally, it should have a surface area ≥ the overall length of the 1/4-wave radiating element. This is often not practical due to size and configuration constraints. In these instances, a designer must make the best use of the area available to create as much ground plane as

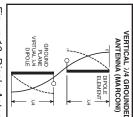


Figure 19: Dipole Antenna

possible in proximity to the base of the antenna. In cases where the antenna remotely located or the antenna is not in close proximity to a circuit boa ground plane, or grounded metal case, a metal plate may be used to maxim the antenna's performance.

- 5. Remove the antenna as far as possible from potential interference sources. A frequency of sufficient amplitude to enter the receiver's front end will redusystem range and can even prevent reception entirely. Switching pov supplies, oscillators, or even relays can also be significant sources of poten interference. The single best weapon against such problems is attention placement and layout. Filter the module's power supply with a high-frequer bypass capacitor. Place adequate ground plane under potential sources of no to shunt noise to ground and prevent it from coupling to the RF stage. Shi noisy board areas whenever practical.
- 6. In some applications, it is advantageous to place the module and antenna away from the main equipment. This can avoid interference problems and allows the antenna to be oriented for optimum performance. Always use 50Ω coax, like RG-174, for the remote feed.

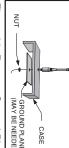


Figure 20: Remote Ground Pla

## **COMMON ANTENNA STYLES**

There are literally hundreds of antenna styles and variations that can be employed with Linx RF modules. Following is a brief discussion of the styles connectors offer outstanding performance at a low price. Application Notes AN-00100, AN-00140, and AN-00500. Linx antennas and most commonly utilized. Additional antenna information can be found in Linx

# 



model. To meet this need, Linx offers a wide variety of straight A whip-style antenna provides outstanding overall performance connectorized mounting styles. and reduced-height whip-style antennas in permanent and performance and cosmetic appeal of a professionally-made wire or rod, but most designers opt for the consistent and stability. A low-cost whip is can be easily fabricated from a

to reduce the overall height of the antenna by using a helical way to minimize the antenna's physical size for compact winding. This reduces the antenna's bandwidth, but is a great applications. This also means that the physical appearance is Its size and natural radiation resistance make it well matched to antenna's overall length. Since a full wavelength is often quite The wavelength of the operational frequency determines an not always an indicator of the antenna's frequency easily determined using the adjacent formula. It is also possible long, a partial 1/2- or 1/4-wave antenna is normally employed. Linx modules. The proper length for a straight 1/4-wave can be

F = operating frequency L = length in feet of



Specialty Styles Linx offers a wide variety of specialized antenna styles. overall antenna size while maintaining reasonable objects, so care must be exercised in layout and placement narrow and the antenna can detune in proximity to other performance. A helical antenna's bandwidth is often quite Many of these styles utilize helical elements to reduce the

#### Loop Style



A loop- or trace-style antenna is normally printed directly on a production. In addition, printed styles are difficult to engineer, PCB dielectric, which can cause consistency issues during applications. They are also very sensitive to changes in layout and antennas are generally inefficient and useful only for short-range usually product specific. Despite the cost advantages, loop-style styles. The element can be made self-resonant or externally product's PCB. This makes it the most cost-effective of antenna analyzer. An improperly designed loop will have a high SWR at the requiring the use of expensive equipment, including a network resonated with discrete components, but its actual layout is desired frequency, which can cause instability in the RF stage.

to a product's PCB. These tiny antennas do not require testing and provide excellent performance in light of their small size. They offer a preferable alternative to the often-problematic "printed" Linx offers low-cost planar and chip antennas that mount directly

### **ONLINE RESOURCES**



www.linxtechnologies.com

- Latest News
- Data Guides
- Application Notes
- Knowledgebase
- Software Updates



If you have questions regarding any Linx product and have Internet acce make www.linxtechnologies.com your first stop. Our website is organized in more. Be sure to visit often! application notes, a comprehensive knowledgebase, FCC information, and mu products and services of Linx. It's all here: manual and software update Linx website gives you instant access to the latest information regarding intuitive format to immediately give you the answers you need. Day or night,

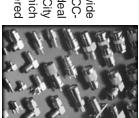
#### www.antennafactor.com

antennas to low-cost whips, domes to which are optimized for use with our RF a diverse array of antenna styles, many of design one to meet your requirements modules. From innovative embeddable likely has an antenna for you, or car Yagis, and even GPS, Antenna Factor The Antenna Factor division of Linx offers



#### www.connectorcity.com

at a remarkably low cost allows standard and custom RF connectors to be offered compliant types such as RP-SMAs that are an ideal selection of high-quality RF connectors, including FCCfocuses on high-volume OEM requirements, which match for our modules and antennas. Connector City Through its Connector City division, Linx offers a wide



Page 16

## LEGAL CONSIDERATIONS

with all laws governing its use in the country of operation. the sale or operation of the device, and agrees to utilize the component in keeping worldwide. The purchaser understands that approvals may be required prior to external components to function. The modules are intended to allow for full Part NOTE: Linx RF modules are designed as component devices that require 15 compliance; however, they are not approved by the FCC or any other agency

clear idea of what is involved in obtaining the necessary approvals to legally market your desire is not only to expedite the design process, but also to assist you in achieving a uncertainty and even fear of the approval and certification process. Here at Linx, our possible and what is legally acceptable in the country where operation is intended. Many completed product. manufacturers have avoided incorporating RF into their products as a When working with RF, a clear distinction must be made between what is technically

compliance testing in our HP / Emco-equipped test center. Final compliance testing is radiates RF energy be approved, that is, tested for compliance and issued a unique included with Linx evaluation kits or may be obtained from the Linx Technologies website, Washington or from your local government bookstore. Excerpts of applicable sections are strongly recommended that a copy be obtained from the Government Printing Office in however, all regulations applicable to this module are contained in Volume 0-19. It is the Federal Communications Commission (FCC). The regulations are contained in Title regulations governing RF devices and the enforcement of them are the responsibility of be issued an ID number that is to be clearly placed on each product manufactured. time, such as UL, CLASS A / B, etc. Once your completed product has passed, you will Many labs can also provide other certifications that the product may require at the same then performed by one of the many independent testing laboratories across the country. identification number. This is a relatively painless process. Linx offers full EMC prewww.linxtechnologies.com. In brief, these rules require that any device that intentionally 47 of the Code of Federal Regulations (CFR). Title 47 is made up of numerous volumes; In the United States, the approval process is actually quite straightforward. The

procedures used to test intentional radiators, such as Linx RF modules, for compliance Questions regarding interpretations of the Part 2 and Part 15 rules or measurement with the technical standards of Part 15, should be addressed to:

Customer Service Branch, MS 1300F2 Federal Communications Commission Equipment Authorization Division 7435 Oakland Mills Road Columbia, MD 21046

Phone: (301) 725-1585 Fax: (301) 344-2050 E-Mail: labinfo@fcc.gov

product abroad, you should contact Linx Technologies to determine the specific suitability of the module to your application. to allow all international standards to be met. If you are considering the export of your International approvals are slightly more complex, although Linx modules are designed

required to address these issues, the additional usefulness and profitability added to a frustration that is typically experienced with a discrete design is eliminated. Approval is product by RF makes the effort more than worthwhile. frequency selected, and physical packaging. While some extra cost and design effort are still dependent on many factors, such as the choice of antennas, correct use of the All Linx modules are designed with the approval process in mind and thus much of the

# ACHIEVING A SUCCESSFUL RF IMPLEMENTATION

vary widely, it is difficult to recommend one dimension to any product. It also means that particular design path, but most projects follow steps of the steps necessary to ensure a successful RF design and approval process is greatly simplified. It bring the product successfully to market. By utilizing additional effort and commitment will be needed to Adding an RF stage brings an exciting new similar to those shown at the right. integration. Since the capabilities of each customer is still important, however, to have an objective view premade RF modules, such as the LR Series, the

and taking advantage of the resources we offer, you commitment. By choosing Linx as your RF partner will not only survive implementing RF, you may even find the process enjoyab Simple" is more than just a motto, it's our that RF is a complex science requiring the highest unusual for a high-volume component manufacturer. antenna design and FCC prequalification) that are caliber of products and support. "Wireless Made technical support, are offered because we recognize These services, along with an exceptional level of notice that Linx offers a variety of services (such as In reviewing this sample design path, you may

COMMENCE SELLING PRODUCT OPTIMIZE USING RF SUMMARY
GENERATED BY LINX CONSULT LINX REGARDING ANTENNA OPTIONS AND DESIGN SEND PRODUCTION-READY PROTOTYPE TO LINX FOR EMC PRESCREENING ORDER EVALUATION KIT(S) CIRCUIT AND DEBUG RESEARCH RF OPTIONS CHOOSE LINX MODULE TEST MODULE(S) WITH BASIC HOOKUP DECIDE TO UTILIZE RF TEST FACILITY RECEIVE FCC ID # LAY OUT BOARD

Typical Steps For

Implementing RF

# HELPFUL APPLICATION NOTES FROM LINX

should be considered to ensure that the modules function correctly and deliv contacting the Linx literature department. depth key areas of RF design and application of Linx products. The wish to obtain one or more of the following application notes, which address the maximum possible performance. As you proceed with your design, you m It is not the intention of this manual to address in depth many of the issues the applications notes are available online at www.linxtechnologies.com or

NOTE	APPLICATION NOTE TITLE
AN-00100	RF 101: Information for the RF Challenged
AN-00125	Considerations For Operation Within The 260-470MHz Band
AN-00130	Modulation Techniques For Low-Cost RF Data Links
AN-00140	The FCC Road: Part 15 From Concept To Approval
AN-00150	Use and Design of T-Attenuation Pads
AN-00160	Considerations For Sending Data Over a Wireless Link
AN-00232	General Considerations For Sending Data With The LC Series
AN-00500	Antennas: Design, Application, Performance

Page



# U.S. CORPORATE HEADQUARTERS

LINX TECHNOLOGIES, INC. 159 ORT LANE MERLIN, OR 97532

PHONE: (541) 471-6256 FAX: (541) 471-6251 www.linxtechnologies.com

#### Disclaimer

Linx Technologies is continually striving to improve the quality and function of its products. For this reason, we reserve the right to make changes to our products without notice. The information contained in this Overview Guide is believed to be accurate as of the time of publication. Specifications are based on representative lot samples. Values may vary from lot-to-lot and are not guaranteed. "Typical" parameters can and do vary over lots and application. Linx Technologies makes no guarantee, warranty, or representation regarding the suitability of any product for use in any specific application. It is the customer's responsibility to verify the suitability of the part for the intended application. NO LINX PRODUCT IS INTENDED FOR USE IN ANY APPLICATION WHERE THE SAFETY OF LIFE OR PROPERTY IS AT RISK.

adjustments, costs, and expenses incurred by Linx Technologies as a result of or arising from any Products refund limited to the original product purchase price. Devices described in this publication may contain sold by Linx Technologies to Customer. Under no conditions will Linx Technologies be responsible for warranty, strict liability, or negligence. Customer assumes all liability (including, without limitation, liability proprietary, patented, or copyrighted techniques, components, or materials. Under no circumstances shall losses arising from the use or failure of the device in any application, other than the repair, replacement, or representatives from and against all claims, damages, actions, suits, proceedings, demands, assessments, hold harmless Linx Technologies and its officers, employees, subsidiaries, affiliates, distributors, and from third parties, arising from the use of the Products. The Customer will indemnify, defend, protect, and for injury to person or property, economic loss, or business interruption) for all claims, including claims theories of recovery asserted by Customer, including, without limitation, breach of contract, breach of OR NON-CONFORMING PRODUCTS OR FOR ANY OTHER BREACH OF CONTRACT BY LINX CUSTOMER'S INCIDENTAL OR CONSEQUENTIAL DAMAGES ARISING IN ANY WAY FROM ANY DEFECTIVE PARTICULAR PURPOSE. IN NO EVENT SHALL LINX TECHNOLOGIES BE LIABLE FOR ANY OF Linx Technologies DISCLAIMS ALL WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A any user be conveyed any license or right to the use or ownership of such items. TECHNOLOGIES. The limitations on Linx Technologies' liability are applicable to any and all claims or

© 2008 by Linx Technologies, Inc. The stylized Linx logo, Linx, "Wireless Made Simple", CipherLinx, and the stylized CL logo are the trademarks of Linx Technologies, Inc. Printed in U.S.A.